

Call for Papers

3 Steps to Contribute a Presentation

Join JSAP

Regular Membership

Admission Fee: 10,000 JPY Annual Due: 10,000 JPY

Graduate Student/
Student Membership

Admission Fee: 3,000 JPY Annual Due: 3,000 JPY

Annual due will be waived for the first year.

Submit

Submission Deadline: June 17 (Tue.), 2025 (17:00, JST)

No late submission is accepted after the deadline.

Submission will open on May 30 (Fri.), 2025

Register

Early-bird Registration (until August 20)

Non-student (JSAP Member/

Partner Society Member*): 12,000 JPY
JSAP Senior Member: 4,000 JPY
Non-student (Non-member): 23,000 JPY
Student/Speaker/Opsite Audiense):

Student(Speaker/Onsite Audience):

3,000 JPY

Student (Online Audience *excluding speaker):

0 JPY

Late Registration (from August 27)

Non-student (JSAP Member /

Partner Society Member*): 18,000 JPY
JSAP Senior Member: 7,000 JPY
Non-student (Non-member): 30,000 JPY
Student(Speaker/Audience): 5,000 JPY

Registration will open on May 30 (Fri.).

(*) JSAP's Partner Societies: APS(American Physical Society), CSOE(Chinese Society for Optical Engineering), EOS(European Optical Society), EPS(European Physical Society), IOP(Institute of Physics), JIEP(Japan Institute of Electronics Packaging), KPS(Korean Physical Society), OPTICA(formerly OSA, The Optical Society), OSJ(Optical Society of Japan), OSK(Optical Society of Korea), PESJ(Physics Education Society of Japan), PSROC(The Physical Society of Republic of China), SPIE(International Society for Optical Engineering), Physics Society of the Philippines(SPP), TPS(Taiwan Photonics Society)

Submission Deadline

June 17 (Tue.), 2025 (5:00pm, JST)

*No late submission is accepted.

Call for Papers

Papers are solicited for the following sessions and symposia.

The date and section of your presentation will be determined by our program committee and informed you on July 2. Your papers may be forwarded from a regular session to a symposium and vice versa.

Regular Sessions

Regular Sessions Focused Session "Al Electronics"		(Voywords)
rocuseu sessioii Ai Electroffics	31.1	(Keywords) Next-generation/advanced semiconductor devices and their AI applications,Brain-inspired computer, neuromorphic, neural network, Computation-In-Memory (CIM), Processing-In-Memory (PIM), memory-based AI, Combinational optimization, annealing, Quantum machine learning, quantum AI, Optical computing, Reservoir computing, physical reservoir, Integration of sensors and AI, AI processing in sensor, Emerging computing technologies: materials/devices
KS Sessions organized by JSAP's Professional Group	KS.1	Solid State Quantum Sensor Group
	KS.2	Quantum Information Engineering Group
	KS.3	Green Transition of Fabrication Group
	KS.4	Group of Quantum Energy Conversion
Interdisciplinary Physics and Related Areas of Science and Technology	1.1	Interdisciplinary and General Physics
	1.2	Education
	1.3	Novel technologies and interdisciplinary engineering
	1.4	Energy conversion, storage, resources and environment
	1.5	Instrumentation, measurement and Metrology
	1.6	Ultrasonics
2. Ionizing Radiation	2.1	Radiation physics, Material development and characteristic evaluation
	2.2	Radiation generators, Detector development, Measurement technology
	2.3	Accelerator technology, Accelerator mass spectrometry and beam analysis
	2.4	Life Sciences, Medical applications, Space and Earth Environment, Radiation Education
3. Optics and Photonics	3.1	Basic optics and frontier of optics
	3.2	Information photonics and image engineering
	3.3	Biomedical optics
	3.4	Laser system and materials
	3.5	Ultrashort-pulse and high-intensity lasers
	3.6	Laser processing
	3.7	Optical measurement, instrumentation, and sensor
	3.8	Terahertz technologies
	3.9	Optical quantum physics and technologies
	3.10	Photonic structures and phenomena
	3.11	Nanoscale optical science and near-field optics
	3.12	Semiconductor optical devices Silicon photonics. Photonics plactronics convergence. Optical control
4 JSAP-OSA Joint Symposia	3.13	Silicon photonics, Photonics-electronics convergence, Optical control Plasmonics and Nanophotonics
*English Session	4.1	Photonics Devices, Photonic Integrated Circuit and Silicon Photonics
English Session	4.3	Laser sources and Laser applications
	4.4	Information Photonics
	4.5	Nanocarbon and 2D Materials
	4.6	Terahertz Photonics
	4.7	Quantum Optics, Nonlinear Optics and Structured Optics
6. Thin Films and Surfaces	6.1	Ferroelectric thin films
	6.2	Carbon-based thin films
	6.3	Oxide electronics
	6.4	Thin films and New materials
	6.5	Surface Physics, Vacuum
	6.6	Probe Microscopy
7. Beam Technology and Nanofabrication	7.1	X-ray technologies
	7.2	Applications and technologies of electron beams
	7.3	Micro/Nano patterning and fabrication
	7.4	Ion beams
	7.5	Atomic/molecular beams and beam-related new technologies
Q. Dianna Florinania	2.4	
	8.1	Plasma production and diagnostics
8. Plasma Electronics *All-English session is scheduled in the section 8.6.	8.2	Plasma deposition of thin film, plasma etching and surface treatment
	8.2 8.3	Plasma deposition of thin film, plasma etching and surface treatment Plasma nanotechnology
	8.2 8.3 8.4	Plasma deposition of thin film, plasma etching and surface treatment Plasma nanotechnology Plasma life sciences
	8.2 8.3 8.4 8.5	Plasma deposition of thin film, plasma etching and surface treatment Plasma nanotechnology Plasma life sciences Plasma phenomena, emerging area of plasmas and their new applications
8. Plasma Electronics *All-English session is scheduled in the section 8.6.	8.2 8.3 8.4	Plasma deposition of thin film, plasma etching and surface treatment Plasma nanotechnology Plasma life sciences

Category		Section
9. Applied Materials Science	9.1	Dielectrics, ferroelectrics
	9.2	Nanoparticles, Nanowires and Nanosheets
	9.3	Nanoelectronics
	9.4	Thermoelectric conversion
	9.5	New functional materials and new phenomena
10. Spintronics and Magnetics	10.1	Emerging materials in spintronics and magnetics (including fabrication and
*English presentation are welcomed in this category. Outstanding	10.1	characterization methodologies)
presentations by student speakers will be awarded.	10.2	Fundamental and exploratory device technologies for spin
	10.3	Spin devices, magnetic memories and storages
	10.4	Spintronics in semiconductor, topological material, superconductor, and
	10.5	multiferroics
44.6	10.5	Application of magnetic field
11. Superconductivity	11.1	Fundamental properties Thin and thick superconducting films, coated conductors and film crustal
	11.2	Thin and thick superconducting films, coated conductors and film crystal growth
	11.3	Critical Current, Superconducting Power Applications
	11.4	Analog applications and their related technologies
	11.5	Junction and circuit fabrication process, digital applications
12. Organic Molecules and Bioelectronics	12.1	Fabrications and Structure Controls
12. Organic Molecules and bioelectronics	12.2	Characterization and Materials Physics
	12.3	Functional Materials and Novel Devices
	12.3	Organic light-emitting devices and organic transistors
	12.4	Organic and hybrid solar cells
	12.5	Nanobiotechnology
	12.7	Biomedical Engineering and Biochips
	12.7	Specific theme: Photoelectric Properties, Device Fabrication and Structural
	12.8	Controls of Organic-Inorganic Hybrid Perovskites
13. Semiconductors	10.1	Fundamental properties, surface and interface, and simulations of Si related
20.0000000	13.1	materials
	13.2	Exploratory Materials, Physical Properties, Devices
	13.3	Insulator technology
	13.4	Si processing /Si based thin film / MEMS / Equipment technology
	13.5	Semiconductor devices/ Interconnect/ Integration technologies
	13.6	Nanostructures, quantum phenomena, and nano quantum devices
	13.7	Compound and power devices, process technology and characterization
	13.8	Optical properties and light-emitting devices
	13.9	Compound solar cells
15. Crystal Engineering	15.1	Bulk crystal growth
, ,	15.2	II-VI and related compounds
	15.3	III-V-group epitaxial crystals, Fundamentals of epitaxy
	15.4	III-V-group nitride crystals
	15.5	Group IV crystals and alloys
	15.6	Group IV Compound Semiconductors (SiC)
	15.7	Crystal characterization, impurities and crystal defects
16. Amorphous and Microcrystalline Materials		Fundamental properties, evaluation, process and devices in disordered
	16.1	materials
	16.2	Energy Harvesting
	16.3	Bulk, thin-film and other silicon-based solar cells
17. Nanocarbon and Two-Dimensional Materials	17.1	Carbon nanotubes & other nanocarbon materials
	17.2	Graphene
	17.3	Layered materials
Joint Session K "Wide bandgap oxide semiconductor materials and	1 27.0	(Keywords)
devices"		thin film growth, characterization of physical properties, transparent
uevices	21.1	conductive oxide film, electronic devices, optical devices, novel functional
		materials & development of novel technologies
Joint Session M "Phonon Engineering"	+	
Joint Session W Friorion Engineering		(Keywords) material development and material properties, measurement methods, theory
		and simulation, thermal conduction and phonon transport, nanoscale and low
	22.1	dimensional system, band engineering, coherent control, phonon polariton,
		magnon, thermal management and design technology, device application,
		thermoelectrics, thermal storage, thermal insulation, micro/nanomechanics,
		heat dissipation, thermal conversion, nano-structure/device fabrication
Joint Cossion N. "Informations"		technology
Joint Session N "Informatincs"		(Keywords)
	22.4	materials informatics, process informatics, measurement informatics, database,
	23.1	data mining, machine learning, deep learning, sparse modeling, statistical
		analysis, causal analysis, optimization, data assimilation, high-throughput,
		automation, robotics

See https://meeting.jsap.or.jp/english/symposium

Submission Guidelines (for contributed papers)

1 Qualification

Speakers of contributed presentation (oral and poster presentations) should be JSAP Regular Members, JSAP Student Members and JSAP's Partner Societies* Members.

*JSAP's partner societies: American Physical Society (APS), CSOE(Chinese Society for Optical Engineering), European Optical Society (EOS), European Physical Society (EPS), Institute of Physics (IOP), JIEP (Japan Institute of Electronics Packaging), Korean Physical Society (KPS), OPTICA (formerly OSA), Optical Society of Japan (OSJ), Optical Society of Korea (OSK), Physics Education Society of Japan (PESJ), Physical Society of Republic of China (PSROC), International Society for Optical Engineering (SPIE), Physics Society of the Philippines(SPP) and Taiwan Photonics Society (TPS).

2. Handling of abstract (PDF)

- 1) Our program committee draws up a program according to speakers' requests. However, the program committee may forward your abstract to another category for the benefit of the overall program.
- 2) JSAP holds the copyright on the submitted abstracts, and all the submitted abstracts will be published on the online conference program and J-STAGE.
- 3) The abstracts submitted to the JSAP-OPTICA Joint Symposia (held only in JSAP Autumn Meeting) will be also published in OPTICA Publishing Group Digital Library. JSAP grants to OPTICA a perpetual, non-exclusive, royalty-free license to use them in any type of media including print or electronic.
- 4) The maximum number of submission per person is 3.

3. JSAP Young Scientist Presentation Award

JSAP Young Scientist Presentation Award will be presented to young JSAP members (under 34 years of age as of April 1, 2026) who have presented outstanding papers.

A poster presentation is not eligible for the award.

To apply for the award, please select "apply" upon online submission. Applicants for the award will be indicated as such in the program.

The applicants for the JSAP Young Scientist Presentation Award are required to present in person. If the applicants make a presentation online, they become unqualified for the award.

4. Poster Award

Poster Award will be presented to JSAP members who give the most outstanding poster presentation of research that represents a valuable contribution to the field of applied physics. The nominees for Poster Award will be selected by the Program Committee based on the content of the extended abstract . No entry is required.

5. Substitute Speaker

If a registered speaker is unavailable on the day due to unavoidable circumstance, the speaker shall be able to appoint a substitute to speak on their behalf. A substitute speaker must be the member mentioned in the preceding 1 and the co-author of the submitted paper. The substitute speaker must register for the conference and complete the payment of the registration fee.

6. No-Show policy

(Oral Session)

If a speaker doesn't show up within 5 minutes of their scheduled presentation time, the presentation will be deemed as "No-Show".

(Poster Session)

If a poster is not put up by 5 minutes after the starting time of the session, the presentation will be deemed as "No-Show".

No-show presentations will be indicated as such on the conference web program.

If any circumstances arise where the registered speaker is unable to present the paper at the meeting, please make sure to inform the secretariat (meeting@jsap.or.jp) in advance.

The absence with prior notification will be indicated as "Absence" on the conference web program.